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## **HUA HONG SEMICONDUCTOR LIMITED**

**華虹半導體有限公司**

*(Incorporated in Hong Kong with limited liability)*

**(Stock Code: 01347)**

### **APPOINTMENT OF EXECUTIVE DIRECTOR AND CHANGE OF PRESIDENT**

This announcement is made pursuant to Rule 13.51(2) of the Rules Governing the Listing of Securities on The Stock Exchange of Hong Kong Limited (the “**Stock Exchange**”) (the “**Listing Rules**”). Reference is made to the announcement of Hua Hong Semiconductor Limited (the “**Company**”) dated 31 December 2024 in relation to, amongst others, the appointment of Mr. Junjun Tang (“**Mr. Tang**”) as the chairman.

The board of directors (the “**Board**”) of the Company hereby announces that with effect from 1 January 2025, Mr. Peng Bai (“**Mr. Bai**”) was appointed as an executive director and the president of the Company. Mr. Tang’s original position as the president of the Company has been succeeded by Mr. Bai, and Mr. Tang will remain as the chairman and an executive director of the Company.

#### **APPOINTMENT OF EXECUTIVE DIRECTOR AND PRESIDENT**

Mr. Bai, aged 62, has been appointed as an executive director and the president of the Company with effect from 1 January 2025. As the president, Mr. Bai is responsible for the day-to-day management of the Company’s business and operations as well as implementation of the Company’s business strategies.

Mr. Bai has over 30 years of experience in the field of integrated circuits manufacturing. Prior to joining the Company, Mr. Bai was the Chief Executive Officer of Rong Semiconductor Corporation (榮芯半導體有限公司), where he had held the position since September 2022. Before that, he served as a process integration engineer, process integration manager, director of yield engineering, director of research and development and vice president, and corporate vice president, successively, at Intel Corporation.

Mr. Bai studied at Peking University and subsequently graduated from the University of Bucharest in 1985 with a Bachelor of Science degree in Physics, and received a Doctor of Philosophy degree in Physics from the Rensselaer Polytechnic Institute in 1991.

Mr. Bai is expected to enter into a service contract with the Company for a term of three years with effect from 1 January 2025, provided that either party may terminate such service contract at any time by giving at least three months' notice in writing. The service contract is expected to provide Mr. Bai with a remuneration package as the president comprising of a base remuneration and performance bonus at a level no less favourable than his predecessor. The remuneration package of Mr. Bai is determined by reference to his duties and responsibilities, as well as the Company's remuneration policy, and will be reviewed by the Board and the Remuneration Committee on an annual basis. In accordance with the Company's articles of association, Mr. Bai's appointment as an executive director is subject to retirement by rotation and re-election at the Company's general meeting.

As at the date of this announcement, Mr. Bai has no interest in any shares of the Company within the meaning of Part XV of the Securities and Futures Ordinance.

Save as disclosed above, (i) Mr. Bai does not have any relationships with any directors, senior management members, substantial shareholders or controlling shareholders (within the meaning of the Listing Rules) of the Company; (ii) Mr. Bai has not held any directorship in any listed public companies in the last three years or any other position with the Company and other members of the Group or other major appointments and professional qualifications; and (iii) there is no further information to be disclosed pursuant to any of the requirements of Rules 13.51(2)(h) to 13.51(2)(v) of the Listing Rules and the Rules Governing the Listing of Stocks on the Science and Technology Innovation Board of the Shanghai Stock Exchange, and there is no other matter which needs to be brought to the attention of the shareholders of the Company in relation to Mr. Bai's appointment.

The Board would like to take this opportunity to welcome Mr. Bai to the Board as an executive director and the president of the Company.

By order of the Board  
**Hua Hong Semiconductor Limited**  
**Mr. Junjun Tang**  
*Chairman and Executive Director*

Hong Kong, 1 January 2025

*As at the date of this announcement, the directors of the Company are:*

***Executive Directors:***

Junjun Tang (*Chairman*)

Peng Bai (*President*)

***Non-Executive Directors:***

Jun Ye

Guodong Sun

Limin Zhou

Chengyan Xiong

***Independent Non-Executive Directors:***

Stephen Tso Tung Chang

Kwai Huen Wong, JP

Songlin Feng